



## Material Content Data Sheet



<b>Sales Product Name</b>				IGD01N120H2		<b>Issued</b>		27. September 2017	
<b>MA#</b>				MA000040540					
<b>Package</b>				PG-TO252-3-11		<b>Weight*</b>		363.82 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.044	0.29	0.29	2870	2870	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		178		
	non noble metal	iron	7439-89-6	0.215	0.06		592		
	non noble metal	copper	7440-50-8	215.017	59.09	59.17	590990	591760	
	non noble metal	aluminium	7429-90-5	0.091	0.02	0.02	249	249	
wire	non noble metal	aluminium	7429-90-5	0.091	0.02	0.02	249	249	
encapsulation	organic material	carbon black	1333-86-4	1.232	0.34		3386		
	inorganic material	antimonytrioxide	1309-64-4	2.464	0.68		6773		
	plastics	brominated resin	-	2.464	0.68		6773		
	plastics	epoxy resin	-	24.641	6.77		67728		
	inorganic material	silicondioxide	60676-86-0	92.404	25.40	33.87	253979	338639	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10280	10280	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	250	251	
solder	non noble metal	tin	7440-31-5	0.023	0.01		63		
	noble metal	silver	7440-22-4	0.029	0.01		79		
	non noble metal	lead	7439-92-1	1.102	0.30	0.32	3029	3171	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		53		
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52711	52780	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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